

## C0805X508CATACTU

Aliases (C0805X508CATAC7800) SMD Comm X8G HT150C Flex, Ceramic, 0.5 pF, +/-0.25 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.6 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	0.6mm MIN
В	0.5mm +/-0.25mm

W	1.25mm +/-0.3mm
T	0.78mm +/-0.20mm
S	0.6mm MIN
В	0.5mm +/-0.25mm
Packaging Specifications	

	Capacitance	0.5 pF
	Measurement Condition	1 MHz 1.0Vrms
	Tolerance	+/-0.25 pF
	Voltage DC	250 VDC
	Dielectric Withstanding Voltage	625 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
ape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

**Specifications** 

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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